

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yuji Egi</td> <td>10/31/2012</td> </tr> <tr> <td>Hideomi Suzawa</td> <td>11/05/2012</td> </tr> <tr> <td>Shinya Sasagawa</td> <td>11/01/2012</td> </tr> </tbody> </table>	Name	Execution Date	Yuji Egi	10/31/2012	Hideomi Suzawa	11/05/2012	Shinya Sasagawa	11/01/2012	
Name	Execution Date								
Yuji Egi	10/31/2012								
Hideomi Suzawa	11/05/2012								
Shinya Sasagawa	11/01/2012								
RECEIVING PARTY DATA									
Name:	Semiconductor Energy Laboratory Co., Ltd.								
Street Address:	398, Hase								
City:	Atsugi-shi, Kanagawa-ken								
State/Country:	JAPAN								
Postal Code:	243-0036								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13677663</td> </tr> </tbody> </table>	Property Type	Number	Application Number:	13677663					
Property Type	Number								
Application Number:	13677663								
CORRESPONDENCE DATA									
Fax Number:	7037662394								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	(571) 434-6789								
Email:	uspto@riplo.com								
Correspondent Name:	Eric J. Robinson								
Address Line 1:	Robinson IP Law Office, P.C.								
Address Line 2:	3975 Fair Ridge Drive, Suite 20 North								
Address Line 4:	Fairfax, VIRGINIA 22033								
ATTORNEY DOCKET NUMBER:	0756-9966								
NAME OF SUBMITTER:	Eric J. Robinson								
Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif									

OP \$40.00 13677663

ASSIGNMENT

Serial No. 13/677,663

Filed November 15, 2012

WHEREAS, Yuji EGI, Hideomi SUZAWA and Shinya SASAGAWA (hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE for which an application for Letters Patent of the United States of America has been executed by the undersigned on _____, and;

WHEREAS, Semiconductor Energy Laboratory Co., Ltd. of 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan and its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to

the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of ROBINSON INTELLECTUAL PROPERTY LAW OFFICE the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 10/31/2012

Signature Yuji Egi
Name Yuji EGI

Date 11/5/2012

Signature Hideomi Suzawa
Name Hideomi SUZAWA

Date 11/1/2012

Signature Shinya SASAGAWA
Name Shinya SASAGAWA

This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed has (have) invented certain new and useful improvements in by at least two other persons who should sign here.

Witness _____

Signature _____

Witness _____

Signature _____

Witness _____

Signature _____